

SPECIFICATION AMENDMENTS:

Please replace the paragraph on page 6, lines 1 through 8, with the following amended paragraph:

--The inorganic substrate 10 is covered by a covering layer 40 and bonded with two organic substrate 20 fixed outside, so that the inorganic substrate 10 is fully covered by the organic substrate 20. The covering layer 40 also includes circuit for providing electrical connections between the passive components and the organic substrate 20. Several inorganic substrates 10 with different passive components can be designed and embedded according to circuit requirements. Each organic substrate 20 is also embedded with unshown passive components, such as capacitors, resistors and inductors, according to the circuit design and improvement of its functions.--

Please replace the paragraph on page 6, lines 17 through 23, with the following amended paragraph:

--FIG. 5 shows a sectional view of a fifth embodiment of the invention. The construction different from that of the fourth embodiment is that the inorganic substrate 10 is covered by a covering layer 40 and bonded with two organic substrates 20 fixed outside, so that the inorganic substrate 10 is fully covered by the two organic substrates 20. The covering layer 40 also includes circuit for providing electrical connections between the passive components and the organic

substrates 20. Several inorganic substrates 10 with different passive components can be designed and embedded according to circuit requirements.--